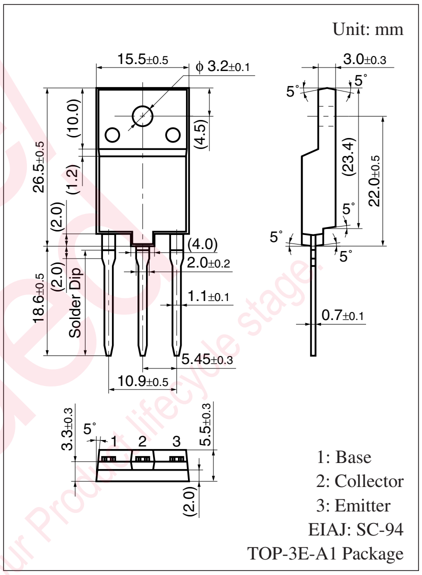
2SC5686

Silicon NPN triple diffusion mesa type

Horizontal deflection output for TV, CRT monitor



■ Features

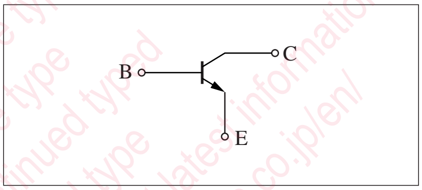
- High breakdown voltage: $V_{CBO} \geq 2000$ V
- High-speed switching: $t_f < 200$ ns
- Wide safe operation area

■ Absolute Maximum Ratings $T_C = 25°C$

Parameter		Symbol	Rating	Unit
Collector-base voltage (Emitter open)		V_{CBO}	2 000	V
Collector-emitter voltage (E-B short)		V_{CES}	2 000	V
Collector-emitter voltage (Base open)		V_{CEO}	600	V
Emitter-base voltage (Collector open)		V_{EBO}	7	V
Base current		I_B	11	A
Collector current		I_C	20	A
Peak collector current *		I_{CP}	30	A
Collector power dissipation		P_C	70	W
	$T_a = 25°C$		3.5	
Junction temperature		T_j	150	°C
Storage temperature		T_{stg}	−55 to +150	°C

Note) *: Non-repetitive peak collector current

Internal Connection

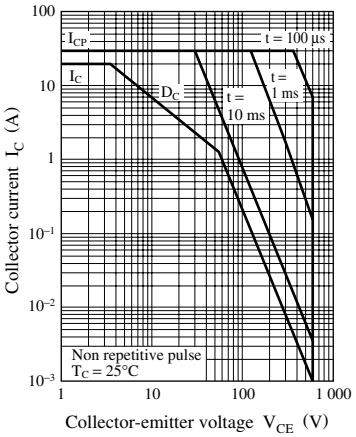


■ Electrical Characteristics $T_C = 25°C \pm 3°C$

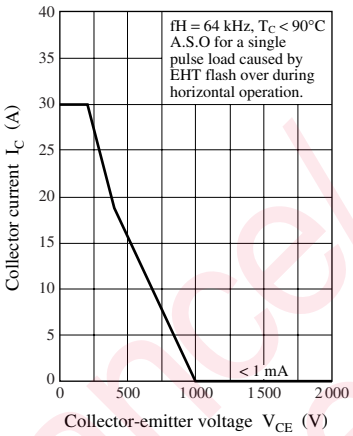
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 1000$ V, $I_E = 0$			50	µA
		$V_{CB} = 2000$ V, $I_E = 0$			1	mA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 7$ V, $I_C = 0$			50	µA
Forward current transfer ratio	h_{FE}	$V_{CE} = 5$ V, $I_C = 10$ A	5		10	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 10$ A, $I_B = 2.5$ A			3	V
Base-emitter saturation voltage	$V_{BE(sat)}$	$I_C = 10$ A, $I_B = 2.5$ A			1.5	V
Transition frequency	f_T	$V_{CE} = 10$ V, $I_C = 0.1$ A, f = 0.5 MHz		3		MHz
Storage time	t_{stg}	$I_C = 10$ A, Resistance loaded			3.0	µs
Fall time	t_f	$I_{B1} = 2.5$ A, $I_{B2} = -5.0$ A			0.2	µs

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

Safe operation area



Safe operation area (Horizontal operation)



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